Build Up HDI (Standard)

HDI12_1+10+1_1,60_17.5_engl

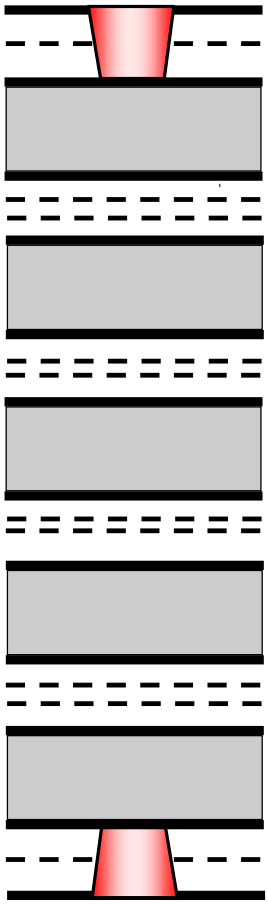
12 - Layers

Core: 0,15 mm Cu 17.5/17.5 µm

WE-Articel No.: **1 + 10 + 1**

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	66	
	2			17,5 µm		16	
			0,150 mm			150	
	3			17,5 µm		16	
					2 x 1080	134	
	4			17,5 µm		16	
			0,150 mm			150	
	5			17,5 µm		16	
					2 x 1080	134	
	6			17,5 µm		16	
			0,150 mm			150	
	7			17,5 µm		16	
					2 x 1080	134	
	8			17,5 µm		16	
			0,150 mm			150	
	9			17,5 µm		16	
					2 x 1080	134	
	10			17,5 µm		16	
			0,150 mm			150	
	11			17,5 µm		16	
					1 x 1080	66	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1602

Note: Lamination thickness for Prepregs depending on layout characteristics.

							Date:	Engineer:
final lamination thickness:	**1,60**	+/-	0,12	mm				
thickness with electro plated Cu:	1,69	+/-	0,15	mm				
total thickness with soldermask	1,75	+/-	0,17	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision	page:
28.03.2006	**S. Keller**	04.05.2006	M.Kress	04.05.2006	R. Schönholz	00	3+